



CBR-SMD RF COG, Ceramic, 9.7 pF, +/-0.5 pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	5.29 mg
Notes	Solder Wave or Solder Reflow.
Shelf Life	78 Weeks
MSL	1

9.7 pF

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
Т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

W	0.8mm +/-0.1mm	Voltage DC	100 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	250 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.168%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms

L	1.6mm +/-0.1mm	Tolerance	+/-0.5 pF
W	0.8mm +/-0.1mm	Voltage DC	100 VDC
Т	0.8mm +/-0.07mm	Dielectric Withstanding Voltage	250 VDC
В	0.4mm +/-0.15mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.168%
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
Packaging Quantity	4000	Insulation Resistance	10 GOhms
		Quality Factor	594

**Specifications** 

Capacitance

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